# Welcome to Stanford Microdevices CD-ROM Wireless Products Catalog



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# Welcome to Stanford Microdevices CD-ROM Wireless Products Catalog About Stanford Microdevices...



### **Catalog Disclaimer**



## **Quality Assurance**



Technical Assistance

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Credits

**Customer Service** 

![](_page_1_Picture_12.jpeg)

![](_page_1_Picture_13.jpeg)

World Wide Web

Stanford Microdevices 1998 Wireless Products Handbook CD-ROM

Concept, Design & Interface

**Beta Test/CD-ROM Duplication** 

**CD** Cover Design

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Contact Information

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![](_page_3_Picture_0.jpeg)

![](_page_4_Figure_0.jpeg)

![](_page_5_Figure_0.jpeg)

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![](_page_7_Figure_0.jpeg)

# **Welcome to Stanford Microdevices CD-ROM Wireless Products Catalog Quality Assurance**

![](_page_8_Picture_1.jpeg)

![](_page_8_Picture_2.jpeg)

Die Attach

![](_page_8_Picture_4.jpeg)

![](_page_8_Picture_5.jpeg)

Solder Profile

**Thermal Data** 

![](_page_8_Picture_8.jpeg)

![](_page_8_Picture_9.jpeg)

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## Welcome to Stanford Microdevices CD-ROM Wireless Products Catalog 50 Ohm Gain Blocks (SMT)

![](_page_9_Figure_1.jpeg)

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![](_page_12_Figure_0.jpeg)

## **About Stanford Microdevices**

### Introduction

Stanford Microdevices primary objective is to consumerize innovative products for the wireless, fiber-optic and CATV markets.

To advance this goal, Stanford Microdevices has formed strategic alliances with foundries that feature leading-edge process technologies and combined it with internal high-volume manufacturing capabilities to produce innovative RFIC's in a cost effective manner.

Over 150 employees in North America and the Pacific Rim develop, manufacture, market and service more than 300 products ranging from small signal components to fully-integrated high-power transceivers. With our broad product line and worldwide distribution network, Stanford Microdevices delivers leading-edge solutions to more than 2000 customers in more than 50 countries.

### **Customer Service and Technical Support**

Through an expansive base of sales offices worldwide, Stanford Microdevices provides our customers with 24-hour service and support.

We offer expert technical support for cellular, PCS, GSM, ISM and wideband applications. Statistical data are available to aid design engineers and fully assembled demo boards are offered to assist in shortening evaluation cycles.

### **Technology Development**

Stanford Microdevices' GaAs Development Group features leading-edge gallium arsenide process technologies, originally developed for stringent defense and space requirements, such as 1-micron HBT and 0.1-micron HFET for low to medium power, high-linearity amplifier applications.

Our Silicon Development Group will introduce its LDMOS (lateral DMOS) products in 1998. Development efforts are also underway in Silicon Germanium and Silicon Carbide for high power applications, as well as Indium Phosphide HEMT (high electron mobility transistor) for low voltage applications.

### Facilities

Stanford Microdevices occupies a total of 100,000 square feet in three locations. We are headquartered in Sunnyvale, California, with a Design and Innovation Center located in Dallas, Texas. Our primary manufacturing facility is in Manila, Philippines.

### **Major Products**

- Cascadable 50-ohm MMIC general purpose amplifiers that span DC-10 GHz in plastic 86, SOT-89 and SOT-363 and ceramic 70 mil package styles.
- 50-ohm MMIC low-noise amplifiers that span DC-3 GHz in plastic 86, MSOP-8 and SOT-363 surface mount packaging.
- Half-watt to 2-watt discrete HFETs in plastic SOT-89 surface mount packaging.
- High-power and high-isolation switches in plastic SO8, MSOP-8 and ceramic SOIC-8 surface mount package styles.
- Half-watt to 4-watt HBT MMIC amplifiers for PCS and cellular applications.
- Low-noise and high power amplifier integrated subassemblies.
- LDMOS products in 1998.
- Millimeter products in 1998.